

Datasheet revision 1.0

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## Solder Wire Sn62/Pb36/Ag2 No-Clean with 2.0% Flux Core 0.3oz Tube

Product Highlights No-Clean Synthetic Flux Core The clear, non-corrosive, non-conductive residue is meant to be left on the board. 2.0% flux core Halogen content: None

## **Specifications**

Alloy: Wire Diameter: Flux Type: Flux Classification: Melting Point: Packaging: Sn62/Pb36/Ag2 0.020" (0.5mm) No-Clean Synthetic ROL0 179°C (354°F) 0.3oz Tube



Yes

Yes

No

## **Test Results**

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Conforms to the following Industry Standards: J-STD-004B, Amendment 1 (Solder Fluxes): J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): RoHS 2 Directive 2011/65/EU: